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METHOD FOR FORMING SEMICONDUCTOR STRUCTURE

Abstract

A method for forming a semiconductor structure is provided. The method includes forming a first passivation layer over an interconnect structure. The first passivation exposes a conductive feature electrically connected to the interconnect structure. The method includes performing an electrical test on the conductive feature. The method includes covering the conductive feature using an oxide material. The method also includes attaching a carrier substrate over the oxide material using a bonding layer.

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Background/Summary

CROSS REFERENCE TO RELATED APPLICATIONS [0001] This application is a Continuation of pending U.S. patent application Ser. No. 17/824,263, filed May 25, 2022 and entitled “METHOD FOR FORMING SEMICONDUCTOR STRUCTURE”, the entirety of which is incorporated by reference herein.”

BACKGROUND

[0002] The semiconductor industry continues to improve the integration density of various electronic components (e.g., transistors, diodes, resistors, capacitors, etc.) by continual reductions in minimum feature size, which allow more components to be integrated into a given area. The individual dies are typically packaged separately. A package not only provides protection for semiconductor devices from environmental contaminants, but also provides a connection interface for the semiconductor devices packaged therein.

[0003] Three dimensional integrated circuits (3DICs) are a recent development in semiconductor packaging in which multiple semiconductor dies are stacked upon one another, such as package-on-package (PoP) and system-in-package (SiP) packaging techniques. Some 3DICs are prepared by placing dies over dies on a semiconductor wafer level. 3DICs provide improved integration density and other advantages, such as faster speeds and higher bandwidth, because of the decreased length of interconnects between the stacked dies, for example. However, there are many challenges related to 3DICs.

Description

BRIEF DESCRIPTION OF THE DRAWINGS

[0004] Aspects of the present disclosure are best understood from the following detailed description when read with the accompanying figures. It should be noted that, in accordance with the standard practice in the industry, various features are not drawn to scale. In fact, the dimensions of the various features may be arbitrarily increased or reduced for clarity of discussion. The figures may be simplified for the sake of clarity to better understand different aspects of the disclosure.

[0005] FIGS. 1, 2A, 2B, 3A, 3B, 4A, 4B, 5A, 5B, 6A, 6B, 7A, 7B, 8A, 8B, 9A, 9B, 10A, and 10B are cross-sectional views illustrating various stages of forming a semiconductor structure, in accordance with some embodiments of the disclosure.

[0006] FIGS. 11-13 are cross-sectional views illustrating various stages of forming a semiconductor structure, in accordance with some embodiments of the disclosure.

DETAILED DESCRIPTION

[0007] The following disclosure provides many different embodiments, or examples, for implementing different features of the provided subject matter. Specific examples of components and arrangements are described below to simplify the present disclosure. These are, of course, merely examples and are not intended to be limiting. For example, the formation of a first feature over or on a second feature in the description that follows may include embodiments in which the first and second features are formed in direct contact, and may also include embodiments in which additional features may be formed between the first and second features, such that the first and second features may not be in direct contact. In addition, the present disclosure may repeat

reference numerals and/or letters in the various examples. This repetition is for the purpose of simplicity and clarity and does not in itself dictate a relationship between the various embodiments and/or configurations discussed.

[0008] Further, spatially relative terms, such as “beneath,” “below,” “lower,” “above,” “upper,” and the like, may be used herein for ease of description to describe one element or feature's relationship to another element(s) or feature(s) as illustrated in the figures. The spatially relative terms are intended to encompass different orientations of the device in use or operation in addition to the orientation depicted in the figures. The apparatus may be otherwise oriented (rotated 90 degrees or at other orientations) and the spatially relative descriptors used herein may likewise be interpreted accordingly.

[0009] Embodiments of semiconductor structures and methods for forming the same are provided. The method for forming the semiconductor structure may include conducting an electrical test prior to the integration of the SoC or SoIC die structure. Accordingly, it is more likely to detect a malfunctioning semiconductor structure as early as possible, thereby the yield of the semiconductor structure may be increased, saving time and money. In addition, the formation of the adhesive layer helps to enhance the attachment between the second passivation layer and the oxide material, increasing the structural strength of the semiconductor structure.

[0010] FIGS. 1, 2A, 2B, 3A, 3B, 4A, 4B, 5A, 5B, 6A, 6B, 7A, 7B, 8A, 8B, 9A, 9B, 10A, and 10B are cross-sectional views illustrating various stages of forming a semiconductor structure **10**, in accordance with some embodiments of the disclosure. The semiconductor structure **10** may be a device wafer including active devices (e.g., transistors) and/or passive devices (e.g., capacitors, inductors, resistors, or the like). In some embodiments, the semiconductor structure **10** is an interposer wafer, which may or may not include active devices and/or passive devices. In accordance with yet another embodiment of the present disclosure, the semiconductor structure **10** is a package substrate strip, which may be package substrates with cores therein or may be core-less package substrates. In subsequent discussion, a device wafer is used as an example of the semiconductor structure **10**. The teaching of the present disclosure may also be applied to interposer wafers, package substrates, or other semiconductor structures, as skilled artisans readily appreciate.

[0011] As shown in FIG. 1, the semiconductor structure **10** includes a semiconductor substrate **100**. In some embodiments, one or more electrical component (not shown) is formed on or in the semiconductor substrate **100**. For example, the electrical component may include transistors (e.g., Complementary Metal-Oxide Semiconductor (CMOS) transistors), resistors, capacitors, inductors, diodes, or any other suitable electrical component, and may be formed using any suitable method, details are not discussed here. In some embodiments, the semiconductor substrate **100** and the electrical component formed thereon may be collectively referred to as the semiconductor substrate **100**. The semiconductor substrate **100** may include a semiconductor material, such as silicon, doped or undoped, or an active layer of a semiconductor-on-insulator (SOI) substrate. The semiconductor substrate **100** may include other semiconductor materials, such as germanium; a compound semiconductor including silicon carbide, gallium arsenic, gallium phosphide, gallium nitride, indium phosphide, indium arsenide, and/or indium antimonide; an alloy semiconductor including SiGe, GaAsP, AlInAs, AlGaAs, GaInAs, GaInP, and/or GaInAsP; or combinations thereof. Other substrates, such as multi-layered or gradient substrates, may also be used.

[0012] In some embodiments, the semiconductor substrate **100** includes a plurality of conductive structures **101** and a plurality of conductive vias **102** electrically connected to the conductive structures **101**. It is noted that the conductive structures **101** and the conductive vias **102** are illustrative, and the present disclosure is not limited thereto. In some embodiments, the conductive structures **101** and the conductive vias **102** include Cu, CuAl, Al, or any other suitable conductive material.

[0013] In some embodiments, an interconnect region **110** is formed on the semiconductor substrate

100. The interconnect region **110** includes at least one inter-layer dielectric (ILD) layer, which is formed over the semiconductor substrate **100**. In accordance with some embodiments, the ILD layer includes silicon oxide, phosphosilicate glass (PSG), borosilicate glass (BSG), boron-doped phosphosilicate glass (BPSG), fluorine-doped silicate glass (FSG), or the like. The ILD layer may be formed using spin coating, Flowable Chemical Vapor Deposition (FCVD), Plasma Enhanced Chemical Vapor Deposition (PECVD), Low Pressure Chemical Vapor Deposition (LPCVD), or the like.

[0014] In addition, the interconnect region **110** further includes a plurality of conductive wires **111** and a plurality of conductive vias **112** electrically connected to the conductive structures **101** for transmitting electrical signals. The conductive wires **111** and the conductive vias **112** may be collectively referred to as an interconnect structure. In some embodiments, the interconnect structure interconnects the electrical components in the semiconductor structure **10** to form functional circuits. In some embodiments, the conductive vias **112** are electrically connected to the conductive wires **111**. In some other embodiments, the conductive vias **112** are electrically isolated from the conductive wires **111**. In some embodiments, the conductive vias **112** are each aligned with the conductive vias **102**. In some other embodiments, the conductive vias **112** are each offset from the conductive vias **102**.

[0015] Next, a plurality of conductive features **120** are formed over the interconnect region **110**, for example, over the conductive vias **112**. Each of the conductive features **120** may be centered with respect to the underlying conductive vias **112**, or may be off-center with respect to the underlying conductive vias **112**. The conductive features **120** may be conductive pads, include an electrically conductive material, such as aluminum, copper or an alloy thereof (e.g., a copper-silver alloy, a copper-cobalt alloy, or the like), and may be formed using a suitable formation method such as electroplating, electroless plating, or the like. The shape of the cross-section of the conductive features **120** may be a rectangular (or square) shape, a concave shape, a polygon shape, or a dome shape (e.g., with a curved upper surface), as examples. Note that in FIG. 1, the sizes (e.g. the width measured in the X-axis) of conductive features **120** are substantially equal to each other. In some embodiments, some of the conductive features **120** are larger (e.g., having a larger width measured in the X-axis) than other conductive features **120**.

[0016] It should be noted that in the following embodiments, the drawings that share corresponding numerals (for example, FIGS. 2A and 2B, FIGS. 3A and 3B, etc.) show different portions of the semiconductor structure **10**. To be more specific, for example, the portions shown in FIGS. 2A and 2B are located at different positions on the X-Y plane, and are located at substantially the same height in the Z axis. However, the present disclosure is not limited thereto.

[0017] As shown in FIGS. 2A and 2B, an etch stop layer (ESL) **125** is formed over the interconnect region **110** and conductive features **120**. In some embodiments, the etch stop layer **125** is conformally formed over the interconnect region **110** and conductive features **120**. In some embodiments, the material of the etch stop layer **125** is made of silicon nitride, silicon oxynitride, and/or other applicable materials. Moreover, the etch stop layer **125** is formed by plasma enhanced CVD, low-pressure CVD, atomic layer deposition (ALD), or other applicable processes. In some embodiments, before forming the etch stop layer **125**, an anti-reflection layer may be (e.g. conformally) formed on the interconnect region **110** and conductive features **120** to facilitate the formation of the etch stop layer **125**, and the etch stop layer **125** is formed on the anti-reflection layer.

[0018] In some embodiments, a first passivation layer **130** is formed over the interconnect structure **106** and the conductive features **120**. The first passivation layer **130** may include a plurality of sub-layers (see, e.g., **131-133** in FIGS. 2A and 2B) and may be formed of one or more suitable dielectric materials such as undoped silicate glass (USG), silicon oxide, silicon nitride, low-k dielectrics such as carbon doped oxides, extremely low-k dielectrics such as porous carbon doped silicon dioxide, combinations of these, or the like. The first passivation layer **130** may be formed

through a process such as chemical vapor deposition (CVD), FCVD, High-Density Plasma CVD (HDP CVD) although any suitable process may be utilized. In some embodiments, the sub-layers **131-133** are all made of different materials.

[0019] In some embodiments, the first passivation layer **130** includes a first sub-layer **131**, a second sub-layer **132**, and a third sub-layer **133**. The first sub-layer **131** is formed over the etch stop layer **125** and the conductive features **120**. In some embodiments, the first sub-layer **131** is substantially conformally formed on the etch stop layer **125**. That is to say, the top surface of the first sub-layer **131** is not planar and has a curved section. In some embodiments, the top surface of the first sub-layer **131** is not parallel to a plane that is substantially parallel to the X-Y plane. For example, the material of the first sub-layer **131** includes undoped silicate glass. Of course, other suitable material may also be adopted.

[0020] In addition, the second sub-layer **132** is formed on the first sub-layer **131**, and a bottom surface of the second sub-layer **132** is conformal to the top surface of the first sub-layer **131**. In some embodiments, the top surface of the second sub-layer **132** is planar and substantially parallel to a plane that is substantially parallel to the X-Y plane. That is to say, the profile of the top surface of the sub-layer **131** is different from the profile of the top surface of the sub-layer **132**.

[0021] In some embodiments, the third sub-layer **133** is formed on the second sub-layer **132**, and therefore the second sub-layer **132** is sandwiched between the first sub-layer **131** and the third sub-layer **133**. In some embodiments, a bottom surface of the third sub-layer **133** is conformal to the top surface of the second sub-layer **132**. In some embodiments, the top surface of the third sub-layer **133** is planar and substantially parallel to a plane that is substantially parallel to the X-Y plane. For example, the material of the third sub-layer **133** includes silicon nitride. Of course, other suitable material may also be adopted. For the sake of clarity, the first sub-layer **131**, the second sub-layer **132**, and the third sub-layer **133** are collectively referred to as the first passivation layer **130**. In some embodiments, the first passivation layer **130** may be a multi-layered structure, and the number of the sub-layers of the first passivation layer **130** may be other than three.

[0022] As shown in FIGS. **3A** and **3B**, a hard mask layer (not shown) may be deposited over the first passivation layer **130**. In some embodiments, the hard mask layer may include a nitrogen-containing material and/or a carbon-containing material. For example, the hard mask layer may include SiOCN, SiCN, SiOC, SiC, SiN, or combinations thereof. In some embodiments, the hard mask layer may be conformally deposited and have a substantially uniform thickness. The hard mask layer may be patterned to form openings. In various embodiments, a photolithography process (e.g., such as exposure and development) may be used to pattern the hard mask layer. An etching process may be performed using the hard mask layer to form first openings **135** in the first passivation layer **130**. In some embodiments, a chemical mechanical planarization (CMP) process may be used to remove the hard mask layer to expose the underlying first passivation layer **130**. Due to the formation of the etch stop layer **125**, the etching process is less likely to damage the conductive features **120**. Each of the first openings **135** exposes the corresponding conductive feature **120**. In some embodiments, the sidewalls of the first passivation layer **130** facing the first openings **135** are inclined. In some other embodiments, the sidewalls of the first passivation layer **130** facing the first openings **135** are vertical and substantially to the Z axis.

[0023] In some embodiments, a plurality of probes **300** may be used to conduct an electrical test (for example, a wafer acceptance test (WAT) or any other test) to the conductive features **120** for determining whether the semiconductor structure **10** performs in a high-quality manner. If the semiconductor structure **10** passes the electrical test, the subsequent processes may be performed. Otherwise, a semiconductor structure **10** that fails the electrical test may be withdrawn, thereby the yield of the semiconductor structure **10** may be increased, saving time and money. In some embodiments, the number of the probes **300** corresponds to the number of the plurality of first openings **135** (which is equal to the number of the conductive features **120**). In some embodiments, the probes **300** are moved to be aligned with the first openings **135** (i.e. the conductive features

120). In some embodiments, the semiconductor structure **10** is moved so as the first openings **135** (i.e. the conductive features **120**) are aligned with the probes **300**.

[0024] As shown in FIGS. **4A** and **4B**, in response to that the semiconductor structure **10** passes the electrical test, the subsequent processes may be performed. In some embodiments, an anti-reflection layer **140** is (e.g. conformally) formed on the top surface and the sidewalls of the first passivation layer **130**, wherein each sidewalls of the first passivation layer **130** face one of the first openings **135**. In addition, an oxide material **145** overfills the first openings **135** and extends over the top surface of the first passivation layer **130**. Similarly, the formation of the anti-reflection layer may facilitate the formation of the oxide material **145**. In some embodiments, a plurality of bonding layers **150** and **155** are formed over the oxide material **145** for bonding a carrier substrate **200** in the subsequent process. In some embodiments, the bonding layers **150** and **155** may be replaced with a single-layered bonding layer or a multi-layered layered bonding layer, as long as the carrier substrate **200** may be firmly bonded to the semiconductor structure **10**.

[0025] As shown in FIGS. **5A** and **5B**, the carrier substrate **200** is provided and configured to provide temporary mechanical and structural support during subsequent processing steps, in accordance with some embodiments. In some embodiments, the carrier substrate **200** may be a wafer. In some embodiments, the carrier substrate **200** includes glass, silicon oxide, aluminum oxide, metal, a combination thereof, and/or the like. The carrier substrate **200** include one or more die structure (not shown) disposed over the carrier substrate **200**. The die structure may be a “known-good-die”. In some embodiments, the one or more die structure may be a system-on-chip (SoC) chip or a system on integrated circuit (SoIC) device that includes two or more chips with integrated function. As the integration of the one or more die structure to the semiconductor structure **10**, the performance of the semiconductor structure **10** may be enhanced, or the semiconductor structure **10** may perform variable function as designed, depending on the integrated die structure(s).

[0026] As shown in FIGS. **6A** and **6B**, after the integration of the one or more die structure, the carrier substrate **200** and the bonding layers **150** and **155** are removed. For example, a chemical mechanical planarization (CMP) process may be used to remove the carrier substrate **200** and the bonding layers **150** and **155** to expose the underlying oxide material **145**. Of course, other suitable planarization processes may also be adopted. In some embodiments, during the removal of the carrier substrate **200** and the bonding layers **150** and **155**, a portion of the oxide material **145** is also removed. That is to say, the oxide material **145** is thinned during the chemical mechanical planarization process (or the planarization process).

[0027] As shown in FIGS. **7A** and **7B**, an adhesive layer **160** is formed over the processed oxide material **145** for attaching a second passivation layer **170** to be formed. For example, the material of the adhesive layer **160** includes undoped silicate glass (USG), SiON, tetraethoxysilane (TEOS) oxide, high-density plasma (HDP) oxide, any other suitable material or a combination thereof. In some embodiments, the adhesive layer **160** may be omitted. The second passivation layer **170** is formed over the oxide material **145**, and attached to the adhesive layer **160** (if the adhesive layer **160** is present). The formation of the adhesive layer **160** helps to enhance the attachment between the second passivation layer **170** and the oxide material **145**, increasing the structural strength of the semiconductor structure. The second passivation layer **170** may be a single-layered structure. However, it is noted that the second passivation layer **170** may include multiple sub-layers, which is similar to the first passivation layer **130**. In some embodiments, the second passivation layer **170** may be formed of one or more suitable dielectric materials such as undoped silicate glass (USG), silicon oxide, silicon nitride, low-k dielectrics such as carbon doped oxides, extremely low-k dielectrics such as porous carbon doped silicon dioxide, combinations of these, or the like. The second passivation layer **170** may be formed through a process such as chemical vapor deposition (CVD), FCVD, High-Density Plasma CVD (HDP CVD) although any suitable process may be utilized. In some embodiments, an anti-reflection layer **180** is formed over the second passivation

layer **170**.

[0028] In some embodiments, a hard mask layer (not shown) may be deposited over the second passivation layer **170** and the anti-reflection layer **180**. In some embodiments, the hard mask layer may include a nitrogen-containing material and/or a carbon-containing material. For example, the hard mask layer may include SiOCN, SiCN, SiOC, SiC, SiN, or combinations thereof. In some embodiments, the hard mask layer may be conformally deposited and have a substantially uniform thickness. The hard mask layer may be patterned to form openings. In various embodiments, a photolithography process (e.g., such as exposure and development) may be used to pattern the hard mask layer. An etching process may be performed using the hard mask layer to form a plurality of second openings **175** to expose the conductive features **120**. In some embodiments, a chemical mechanical planarization (CMP) process may be used to remove the hard mask layer.

[0029] As shown in FIGS. **8A** and **8B**, the second openings **175** are spaced apart from the first openings **135**. In some embodiments, the size of the portion of the conductive features **120** exposed by the first openings **135** (see, for example, FIG. **3A**) is substantially the same as the size of the portion of the conductive features **120** exposed by the second openings **175**. To be more specific, the size of the exposed portion of the conductive features **120** may be measured as a width or an area on a plane that is substantially coplanar to the X-Y plane.

[0030] As shown in FIGS. **9A** and **9B**, after the formation of the second openings **175**, the anti-reflection layer **180** is removed, and the probes **300** may be used to conduct an electrical test (for example, a wafer acceptance test (WAT) or any other test) to the conductive features **120** for determining whether the semiconductor structure **10** performs in a high-quality manner. If the semiconductor structure **10** passes the electrical test, the subsequent processes may be performed. Otherwise, a semiconductor structure **10** that fails the electrical test may be withdrawn. By conducting multiple electrical tests at different stages of the process of manufacturing the semiconductor structure **10**, it is more likely to detect a malfunctioning semiconductor structure **10** as early as possible, thereby the yield of the semiconductor structure **10** may be increased, saving time and money. In some embodiments, the anti-reflection layer **180** is removed before the electrical test is conducted by the probes **300**. In some other embodiments, the anti-reflection layer **180** is removed after the electrical test is conducted by the probes **300**.

[0031] In some embodiments, the number of the probes **300** corresponds to the number of the plurality of second openings **175** (which is equal to the number of the conductive features **120**). In some embodiments, the probes **300** are moved to be aligned with the second openings **175** (i.e. the conductive features **120**). In some embodiments, the semiconductor structure **10** is moved so as the second openings **175** (i.e. the conductive features **120**) are aligned with the probes **300**. In some embodiments, the probes **300** shown in FIG. **9B** are the same as the probes **300** shown in FIG. **3A** and configured to conduct the identical electrical test. In some other embodiments, the probes **300** shown in FIG. **9B** are different from the probes **300** shown in FIG. **3A** and configured to conduct different electrical tests.

[0032] As shown in FIGS. **10A** and **10B**, the second passivation layer **170** and the adhesive layer **160** (if the adhesive layer **160** is present) are removed for forming a plurality of bump structures. In some embodiments, a polymeric layer **185** may be formed over the first passivation layer **130** and on the surfaces of the second openings **175**. The polymeric layer **185** may include polyimide (PI). The polymeric layer **185** may be conformally deposited over the first passivation layer **130** and into the second openings **175** using a suitable deposition technique, such as spin-coating. In some embodiments, a baking process may be performed after deposition of the polymeric layer **185**. The deposited polymeric layer **185** may then be patterned using a suitable combination of photolithography processes (e.g., such as photoresist deposition, exposure, and development) to form an etch mask, and an etching process may be performed using the etch mask to expose top surfaces of the conductive features **120**. A plurality of conductive bump structures **190** may be formed in the second openings **175**. The conductive bump structures **190** may include conductive

materials with low resistivity, such as solder or solder alloy. Exemplary elements included in the solder alloy include Sn, Pb, Ag, Cu, Ni, Bi or combinations thereof.

[0033] In some embodiments, the conductive bump structures **190** may also be formed in the first openings **135**. To be more specific, the anti-reflection layer **140** on the sidewalls of the first passivation layer **130** and the oxide material **145** in the first openings **135** are removed by, for example, an etching process. Accordingly, the polymeric layer **185** may be formed over the first passivation layer **130** and on the surfaces of the first openings **135**, and the conductive bump structures **190** may be formed in the first openings **135**.

[0034] FIGS. **11-13** are cross-sectional views illustrating various stages of forming a semiconductor structure **10**, in accordance with some embodiments of the disclosure. It is noted that the embodiment shown in FIGS. **11-13** may continue from the embodiment shown in FIG. **7A**. That is to say, the discussion of the embodiments shown in FIGS. **1** through **7A** also applies to the embodiment shown in FIGS. **11-13**. For the sake of simplicity, the repeated elements/portions will be labeled as the same numerals, and the detailed discussion of these elements/portions will not be repeated in the following paragraphs.

[0035] In some embodiments, a hard mask layer (not shown) may be deposited over the second passivation layer **170** and the anti-reflection layer **180**. In some embodiments, the hard mask layer may include a nitrogen-containing material and/or a carbon-containing material. For example, the hard mask layer may include SiOCN, SiCN, SiOC, SiC, SiN, or combinations thereof. In some embodiments, the hard mask layer may be conformally deposited and have a substantially uniform thickness. The hard mask layer may be patterned to form openings. In various embodiments, a photolithography process (e.g., such as exposure and development) may be used to pattern the hard mask layer. An etching process may be performed using the hard mask layer to form a plurality of second openings **175** to expose the conductive features **120**. In some embodiments, a chemical mechanical planarization (CMP) process may be used to remove the hard mask layer. As shown in FIG. **11**, the second openings **175** expose the same portion of the conductive features as the first openings **135**. To be more specific, the anti-reflection layer **140** on the sidewalls of the first passivation layer **130** and the oxide material **145** in the first openings **135** are removed by the etching process forming the second openings **175**.

[0036] As shown in FIG. **12**, after the formation of the second openings **175**, the anti-reflection layer **180** is removed, and the probes **300** may be used to conduct an electrical test (for example, a wafer acceptance test (WAT) or any other test) on the conductive features **120** for determining whether the semiconductor structure **10** performs in a high-quality manner. If the semiconductor structure **10** passes the electrical test, the subsequent processes may be performed. Otherwise, a semiconductor structure **10** that fails the electrical test may be withdrawn. It is noted that in the present embodiment, the electrical tests are performed to the same conductive features **120**. In some embodiments, the anti-reflection layer **180** is removed before the electrical test is conducted by the probes **300**. In some other embodiments, the anti-reflection layer **180** is removed after the electrical test is conducted by the probes **300**.

[0037] In some embodiments, the number of the probes **300** corresponds to the number of the plurality of second openings **175** (which is equal to the number of the conductive features **120**). In some embodiments, the probes **300** are moved to be aligned with the second openings **175** (i.e. the conductive features **120**). In some embodiments, the semiconductor structure **10** is moved so as the second openings **175** (i.e. the conductive features **120**) are aligned with the probes **300**. In some embodiments, the probes **300** shown in FIG. **12** are the same as the probes **300** shown in FIG. **3A** and configured to conduct the identical electrical test. In some other embodiments, the probes **300** shown in FIG. **12** are different from the probes **300** shown in FIG. **3A** and configured to conduct different electrical tests.

[0038] As shown in FIG. **13**, the second passivation layer **170** and the adhesive layer **160** (if the adhesive layer **160** is present) are removed for forming a plurality of bump structures. In some

embodiments, a polymeric layer **185** may be formed over the first passivation layer **130** and on the surfaces of the second openings **175**. The polymeric layer **185** may include polyimide (PI). The polymeric layer **185** may be conformally deposited over the first passivation layer **130** and into the second openings **175** using a suitable deposition technique, such as spin-coating. In some embodiments, a baking process may be performed after deposition of the polymeric layer **185**. The deposited polymeric layer **185** may then be patterned using a suitable combination of photolithography processes (e.g., such as photoresist deposition, exposure, and development) to form an etch mask, and an etching process may be performed using the etch mask to expose top surfaces of the conductive features **120**. A plurality of conductive bump structures **190** may be formed in the second openings **175**. The conductive bump structures **190** may include conductive materials with low resistivity, such as solder or solder alloy. Exemplary elements included in the solder alloy include Sn, Pb, Ag, Cu, Ni, Bi or combinations thereof.

[0039] Other features and processes may also be included. For example, testing structures may be included to aid in the verification testing of the 3D packaging or 3DIC devices. The testing structures may include, for example, test pads formed in a redistribution layer or on a substrate that allows the testing of the 3D packaging or 3DIC, the use of probes and/or probe cards, and the like. The verification testing may be performed on intermediate structures as well as the final structure. Additionally, the structures and methods disclosed herein may be used in conjunction with testing methodologies that incorporate intermediate verification of known good dies to increase the yield and decrease costs.

[0040] As described above, the present disclosure is directed to conducting multiple electrical tests at different stages of the process of manufacturing the semiconductor structure, it is more likely to detect a malfunctioning semiconductor structure as early as possible, thereby the yield of the semiconductor structure may be increased, saving time and money. In addition, the formation of the adhesive layer helps to enhance the attachment between the second passivation layer and the oxide material, increasing the structural strength of the semiconductor structure.

[0041] In accordance with some embodiments, a method for forming a semiconductor structure is provided. The method includes forming a first passivation layer over an interconnect structure. The first passivation exposes a conductive feature electrically connected to the interconnect structure. The method includes performing an electrical test on the conductive feature. The method includes covering the conductive feature using an oxide material. The method also includes attaching a carrier substrate over the oxide material using a bonding layer.

[0042] In accordance with some embodiments, a method for forming a semiconductor structure is provided. The method includes forming a first passivation layer over a conductive feature over a substrate. The method includes etching the first passivation layer to form a first opening. The first opening overlaps the conductive feature in a normal direction of the substrate. The method includes performing a first electrical test on the conductive feature via the first opening. The method includes overfilling the first opening with an oxide material. The method includes attaching a carrier substrate over the oxide material. The method includes integrating at least one die structure over the substrate. The method includes also removing the carrier substrate after the at least one die structure is integrated over the substrate.

[0043] In accordance with some embodiments, a method for forming a semiconductor structure is provided. The method includes forming a first passivation layer over a conductive feature electrically connected to an interconnect structure. The method includes etching the first passivation layer to form a first opening exposing a portion of the conductive feature. The method includes performing a first electrical test on the conductive feature. The method includes filling the first opening with an oxide material. The method includes etching the oxide material to form a second opening exposing the portion of the conductive feature. The method also includes performing a second electrical test on the conductive feature via the second opening.

[0044] The foregoing outlines features of several embodiments so that those skilled in the art may

better understand the aspects of the present disclosure. Those skilled in the art should appreciate that they may readily use the present disclosure as a basis for designing or modifying other processes and structures for carrying out the same purposes and/or achieving the same advantages of the embodiments introduced herein. Those skilled in the art should also realize that such equivalent constructions do not depart from the spirit and scope of the present disclosure, and that they may make various changes, substitutions, and alterations herein without departing from the spirit and scope of the present disclosure.

Claims

1. A method for forming a semiconductor structure, comprising: forming a first passivation layer over an interconnect structure, wherein the first passivation exposes a conductive feature electrically connected to the interconnect structure; performing an electrical test on the conductive feature; covering the conductive feature using an oxide material; and attaching a carrier substrate over the oxide material using a bonding layer.
2. The method as claimed in claim 1, wherein forming the first passivation layer further comprises sequentially forming a plurality of sub-layer having different materials.
3. The method as claimed in claim 1, wherein forming the first passivation layer further comprises etching a tapered opening in the first passivation layer.
4. The method as claimed in claim 3, wherein performing the electrical test on the conductive feature comprises using a probe to detect the conductive feature via the tapered opening.
5. The method as claimed in claim 1, further comprising: planarizing the oxide material, wherein a top surface of the oxide material is higher than a top surface of the first passivation layer; forming an adhesive layer over the oxide material; and forming a second passivation layer over the adhesive layer.
6. The method as claimed in claim 5, further comprising: forming an anti-reflection layer over the second passivation layer; and removing the anti-reflection layer.
7. The method as claimed in claim 6, further comprising: etching the anti-reflection layer, the second passivation layer, and the oxide material to form an opening; and forming a bump structure in the opening.
8. A method for forming a semiconductor structure, comprising: forming a first passivation layer over a conductive feature over a substrate; etching the first passivation layer to form a first opening, wherein the first opening overlaps the conductive feature in a normal direction of the substrate; performing a first electrical test on the conductive feature via the first opening; overfilling the first opening with an oxide material; attaching a carrier substrate over the oxide material; integrating at least one die structure over the substrate; and removing the carrier substrate after the at least one die structure is integrated over the substrate.
9. The method as claimed in claim 8, further comprising: forming a second passivation layer over the oxide material; forming an anti-reflection layer over the second passivation layer; and forming a second opening to penetrate the first passivation layer, the second passivation layer, and the anti-reflection layer.
10. The method as claimed in claim 9, wherein the second opening exposes the conductive feature.
11. The method as claimed in claim 10, wherein a bottom width of the first opening exposing the conductive feature is substantially the same as a bottom width of the second opening exposing the conductive feature.
12. The method as claimed in claim 9, further comprising: removing the anti-reflection layer after the second opening is formed; and forming a bump structure in the second opening.
13. The method as claimed in claim 12, further comprising: performing a second electrical test on the conductive feature via the second opening before removing the anti-reflection layer.
14. The method as claimed in claim 9, wherein a depth of the second opening is greater than a

depth of the first opening.

15. The method as claimed in claim 9, wherein forming the second opening comprises removing the oxide material filled in the first opening.

16. A method for forming a semiconductor structure, comprising: forming a first passivation layer over a conductive feature electrically connected to an interconnect structure; etching the first passivation layer to form a first opening exposing a portion of the conductive feature; performing a first electrical test on the conductive feature; filling the first opening with an oxide material; etching the oxide material to form a second opening exposing the portion of the conductive feature; and performing a second electrical test on the conductive feature via the second opening.

17. The method as claimed in claim 16, further comprising: forming a first anti-reflection layer over the first passivation layer; and removing the first anti-reflection layer while forming the second opening.

18. The method as claimed in claim 16, further comprising: forming a second anti-reflection layer over the second passivation layer prior to forming the second opening; and removing the second anti-reflection layer after forming the second opening.

19. The method as claimed in claim 16, further comprising: forming a second passivation layer over the oxide material; and etching the second passivation layer to form the second opening.

20. The method as claimed in claim 16, further comprising: forming a bump structure in the second opening after the second electrical test is performed.
